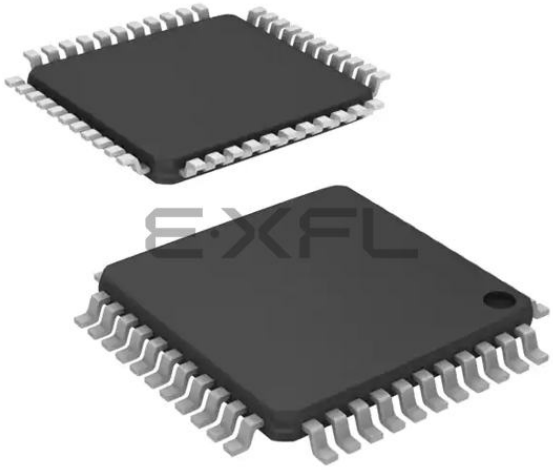

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf45k22t-i-pt

TABLE 1-2: PIC18(L)F2XK22 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Number		Pin Name	Pin Type	Buffer Type	Description
PDIP, SOIC	QFN, UQFN				
9	6	RA7/CLKI/OSC1			
		RA7	I/O	TTL	Digital I/O.
		CLKI	I	CMOS	External clock source input. Always associated with pin function OSC1.
		OSC1	I	ST	Oscillator crystal input or external clock source input ST buffer when configured in RC mode; CMOS otherwise.
21	18	RB0/INT0/CCP4/FLT0/SRI/$\overline{SS2}$/AN12			
		RB0	I/O	TTL	Digital I/O.
		INT0	I	ST	External interrupt 0.
		CCP4	I/O	ST	Capture 4 input/Compare 4 output/PWM 4 output.
		FLT0	I	ST	PWM Fault input for ECCP Auto-Shutdown.
		SRI	I	ST	SR latch input.
		$\overline{SS2}$	I	TTL	SPI slave select input (MSSP).
		AN12	I	Analog	Analog input 12.
22	19	RB1/INT1/P1C/SCK2/SCL2/C12IN3-/AN10			
		RB1	I/O	TTL	Digital I/O.
		INT1	I	ST	External interrupt 1.
		P1C	O	CMOS	Enhanced CCP1 PWM output.
		SCK2	I/O	ST	Synchronous serial clock input/output for SPI mode (MSSP).
		SCL2	I/O	ST	Synchronous serial clock input/output for I^2C mode (MSSP).
		C12IN3-	I	Analog	Comparators C1 and C2 inverting input.
		AN10	I	Analog	Analog input 10.
23	20	RB2/INT2/CTED1/P1B/SDI2/SDA2/AN8			
		RB2	I/O	TTL	Digital I/O.
		INT2	I	ST	External interrupt 2.
		CTED1	I	ST	CTMU Edge 1 input.
		P1B	O	CMOS	Enhanced CCP1 PWM output.
		SDI2	I	ST	SPI data in (MSSP).
		SDA2	I/O	ST	I^2C data I/O (MSSP).
		AN8	I	Analog	Analog input 8.
24	21	RB3/CTED2/P2A/CCP2/SDO2/C12IN2-/AN9			
		RB3	I/O	TTL	Digital I/O.
		CTED2	I	ST	CTMU Edge 2 input.
		P2A	O	CMOS	Enhanced CCP2 PWM output.
		CCP2**(2)**	I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
		SDO2	O	—	SPI data out (MSSP).
		C12IN2-	I	Analog	Comparators C1 and C2 inverting input.
		AN9	I	Analog	Analog input 9.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power.

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

TABLE 1-2: PIC18(L)F2XK22 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Number		Pin Name	Pin Type	Buffer Type	Description
PDIP, SOIC	QFN, UQFN				
25	22	RB4/IOC0/P1D/T5G/AN11			
		RB4	I/O	TTL	Digital I/O.
		IOC0	I	TTL	Interrupt-on-change pin.
		P1D	O	CMOS	Enhanced CCP1 PWM output.
		T5G	I	ST	Timer5 external clock gate input.
		AN11	I	Analog	Analog input 11.
26	23	RB5/IOC1/P2B/P3A/CCP3/T3CKI/T1G/AN13			
		RB5	I/O	TTL	Digital I/O.
		IOC1	I	TTL	Interrupt-on-change pin.
		P2B(1)	O	CMOS	Enhanced CCP2 PWM output.
		P3A(1)	O	CMOS	Enhanced CCP3 PWM output.
		CCP3(1)	I/O	ST	Capture 3 input/Compare 3 output/PWM 3 output.
		T3CKI(2)	I	ST	Timer3 clock input.
		T1G	I	ST	Timer1 external clock gate input.
		AN13	I	Analog	Analog input 13.
27	24	RB6/IOC2/TX2/CK2/PGC			
		RB6	I/O	TTL	Digital I/O.
		IOC2	I	TTL	Interrupt-on-change pin.
		TX2	O	—	EUSART asynchronous transmit.
		CK2	I/O	ST	EUSART synchronous clock (see related RXx/DTx).
		PGC	I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
28	25	RB7/IOC3/RX2/DT2/PGD			
		RB7	I/O	TTL	Digital I/O.
		IOC3	I	TTL	Interrupt-on-change pin.
		RX2	I	ST	EUSART asynchronous receive.
		DT2	I/O	ST	EUSART synchronous data (see related TXx/CKx).
		PGD	I/O	ST	In-Circuit Debugger and ICSP™ programming data pin.
11	8	RC0/P2B/T3CKI/T3G/T1CKI/SOSCO			
		RC0	I/O	ST	Digital I/O.
		P2B(2)	O	CMOS	Enhanced CCP1 PWM output.
		T3CKI(1)	I	ST	Timer3 clock input.
		T3G	I	ST	Timer3 external clock gate input.
		T1CKI	I	ST	Timer1 clock input.
		SOSCO	O	—	Secondary oscillator output.
12	9	RC1/P2A/CCP2/SOSCI			
		RC1	I/O	ST	Digital I/O.
		P2A	O	CMOS	Enhanced CCP2 PWM output.
		CCP2(1)	I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
		SOSCI	I	Analog	Secondary oscillator input.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power.

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

TABLE 10-1: PORTA I/O SUMMARY

Pin Name	Function	TRIS Setting	ANSEL Setting	Pin Type	Buffer Type	Description
RA0/C12IN0-/AN0	RA0	0	0	O	DIG	LATA<0> data output; not affected by analog input.
		1	0	I	TTL	PORTA<0> data input; disabled when analog input enabled.
	C12IN0-	1	1	I	AN	Comparators C1 and C2 inverting input.
	AN0	1	1	I	AN	Analog input 0.
RA1/C12IN1-/AN1	RA1	0	0	O	DIG	LATA<1> data output; not affected by analog input.
		1	0	I	TTL	PORTA<1> data input; disabled when analog input enabled.
	C12IN1-	1	1	I	AN	Comparators C1 and C2 inverting input.
	AN1	1	1	I	AN	Analog input 1.
RA2/C2IN+/AN2/ DACOUT/VREF-	RA2	0	0	O	DIG	LATA<2> data output; not affected by analog input; disabled when DACOUT enabled.
		1	0	I	TTL	PORTA<2> data input; disabled when analog input enabled; disabled when DACOUT enabled.
	C2IN+	1	1	I	AN	Comparator C2 non-inverting input.
	AN2	1	1	I	AN	Analog output 2.
	DACOUT	x	1	O	AN	DAC Reference output.
	VREF-	1	1	I	AN	A/D reference voltage (low) input.
RA3/C1IN+/AN3/ VREF+	RA3	0		O	DIG	LATA<3> data output; not affected by analog input.
		1	0	I	TTL	PORTA<3> data input; disabled when analog input enabled.
	C1IN+	1	1	I	AN	Comparator C1 non-inverting input.
	AN3	1	1	I	AN	Analog input 3.
	VREF+	1	1	I	AN	A/D reference voltage (high) input.
RA4/CCP5/C1OUT/ SRQ/T0CKI	RA4	0	—	O	DIG	LATA<4> data output.
		1	—	I	ST	PORTA<4> data input; default configuration on POR.
	CCP5	0	—	O	DIG	CCP5 Compare output/PWM output, takes priority over RA4 output.
		1	—	I	ST	Capture 5 input/Compare 5 output/ PWM 5 output.
	C1OUT	0	—	O	DIG	Comparator C1 output.
	SRQ	0	—	O	DIG	SR latch Q output; take priority over CCP 5 output.
	T0CKI	1	—	I	ST	Timer0 external clock input.
RA5/C2OUT/SRNQ/ SS1/ HLVDIN/AN4	RA5	0	0	O	DIG	LATA<5> data output; not affected by analog input.
		1	0	I	TTL	PORTA<5> data input; disabled when analog input enabled.
	C2OUT	0	0	O	DIG	Comparator C2 output.
	SRNQ	0	0	O	DIG	SR latch $\overline{Q}$ output.
	$\overline{SS1}$	1	0	I	TTL	SPI slave select input (MSSP1).
	HLVDIN	1	1	I	AN	High/Low-Voltage Detect input.
	AN4	1	1	I	AN	A/D input 4.
RA6/CLKO/OSC2	RA6	0	—	O	DIG	LATA<6> data output; enabled in INTOSC modes when CLKO is not enabled.
		1	—	I	TTL	PORTA<6> data input; enabled in INTOSC modes when CLKO is not enabled.
	CLKO	x	—	O	DIG	In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
	OSC2	x	—	O	XTAL	Oscillator crystal output; connects to crystal or resonator in Crystal Oscillator mode.
RA7/CLKI/OSC1	RA7	0	—	O	DIG	LATA<7> data output; disabled in external oscillator modes.
		1	—	I	TTL	PORTA<7> data input; disabled in external oscillator modes.
	CLKI	x	—	I	AN	External clock source input; always associated with pin function OSC1.
	OSC1	x	—	I	XTAL	Oscillator crystal input or external clock source input ST buffer when configured in RC mode; CMOS otherwise.

Legend: AN = Analog input or output; TTL = TTL compatible input; HV = High Voltage; OD = Open Drain; XTAL = Crystal; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C.

10.7 Port Analog Control

Most port pins are multiplexed with analog functions such as the Analog-to-Digital Converter and comparators. When these I/O pins are to be used as analog inputs it is necessary to disable the digital input buffer to avoid excessive current caused by improper biasing of the digital input. Individual control of the digital input buffers on pins which share analog functions is provided by the ANSELA, ANSELB, ANSELC, ANSELD and ANSELE registers. Setting an ANSx bit high will disable the associated digital input buffer and cause all reads of that pin to return '0' while allowing analog functions of that pin to operate correctly.

The state of the ANSx bits has no affect on digital output functions. A pin with the associated TRISx bit clear and ANSx bit set will still operate as a digital output but the input mode will be analog. This can cause unexpected behavior when performing read-modify-write operations on the affected port.

All ANSEL register bits default to '1' upon POR and BOR, disabling digital inputs for their associated port pins. All TRIS register bits default to '1' upon POR or BOR, disabling digital outputs for their associated port pins. As a result, all port pins that have an ANSEL register will default to analog inputs upon POR or BOR.

10.8 Port Slew Rate Control

The output slew rate of each port is programmable to select either the standard transition rate or a reduced transition rate of approximately 0.1 times the standard to minimize EMI. The reduced transition time is the default slew rate for all ports.

10.9 Register Definitions – Port Control

REGISTER 10-1: PORTX(1): PORTx REGISTER

R/W-u/x	R/W-u/x	R/W-u/x	R/W-u/x	R/W-u/x	R/W-u/x	R/W-u/x	R/W-u/x
Rx7	Rx6	Rx5	Rx4	Rx3	Rx2	Rx1	Rx0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
-n/n = Value at POR and BOR/Value at all other Resets		

bit 7-0 **Rx<7:0>:** PORTx I/O bit values(2)

Note 1: Register Description for PORTA, PORTB, PORTC and PORTD.

2: Writes to PORTx are written to corresponding LATx register. Reads from PORTx register is return of I/O pin values.

TABLE 14-10: REGISTERS ASSOCIATED WITH STANDARD PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				198
CCP2CON	P2M<1:0>		DC2B<1:0>		CCP2M<3:0>				198
CCP3CON	P3M<1:0>		DC3B<1:0>		CCP3M<3:0>				198
CCP4CON	—	—	DC4B<1:0>		CCP4M<3:0>				198
CCP5CON	—	—	DC5B<1:0>		CCP5M<3:0>				198
CCPTMRS0	C3TSEL<1:0>		—	C2TSEL<1:0>		—	C1TSEL<1:0>		201
CCPTMRS1	—	—	—	—	C5TSEL<1:0>		C4TSEL<1:0>		201
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR1	—	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	121
IPR2	OSCFIP	C1IP	C2IP	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	122
IPR4	—	—	—	—	—	CCP5IP	CCP4IP	CCP3IP	124
PIE1	—	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	117
PIE2	OSCFIE	C1IE	C2IE	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	118
PIE4	—	—	—	—	—	CCP5IE	CCP4IE	CCP3IE	120
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	112
PIR2	OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	113
PIR4	—	—	—	—	—	CCP5IF	CCP4IF	CCP3IF	115
PMD0	UART2MD	UART1MD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	52
PMD1	MSSP2MD	MSSP1MD	—	CCP5MD	CCP4MD	CCP3MD	CCP2MD	CCP1MD	53
PR2	Timer2 Period Register								—
PR4	Timer4 Period Register								—
PR6	Timer6 Period Register								—
T2CON	—	T2OUTPS<3:0>				TMR2ON	T2CKPS<1:0>		166
T4CON	—	T4OUTPS<3:0>				TMR4ON	T4CKPS<1:0>		166
T6CON	—	T6OUTPS<3:0>				TMR6ON	T6CKPS<1:0>		166
TMR2	Timer2 Register								—
TMR4	Timer4 Register								—
TMR6	Timer6 Register								—
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	151
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	151
TRISD(1)	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	151
TRISE	WPUE3	—	—	—	—	TRISE2(1)	TRISE1(1)	TRISE0(1)	151

Legend: — = Unimplemented location, read as '0'. Shaded bits are not used by Standard PWM mode.

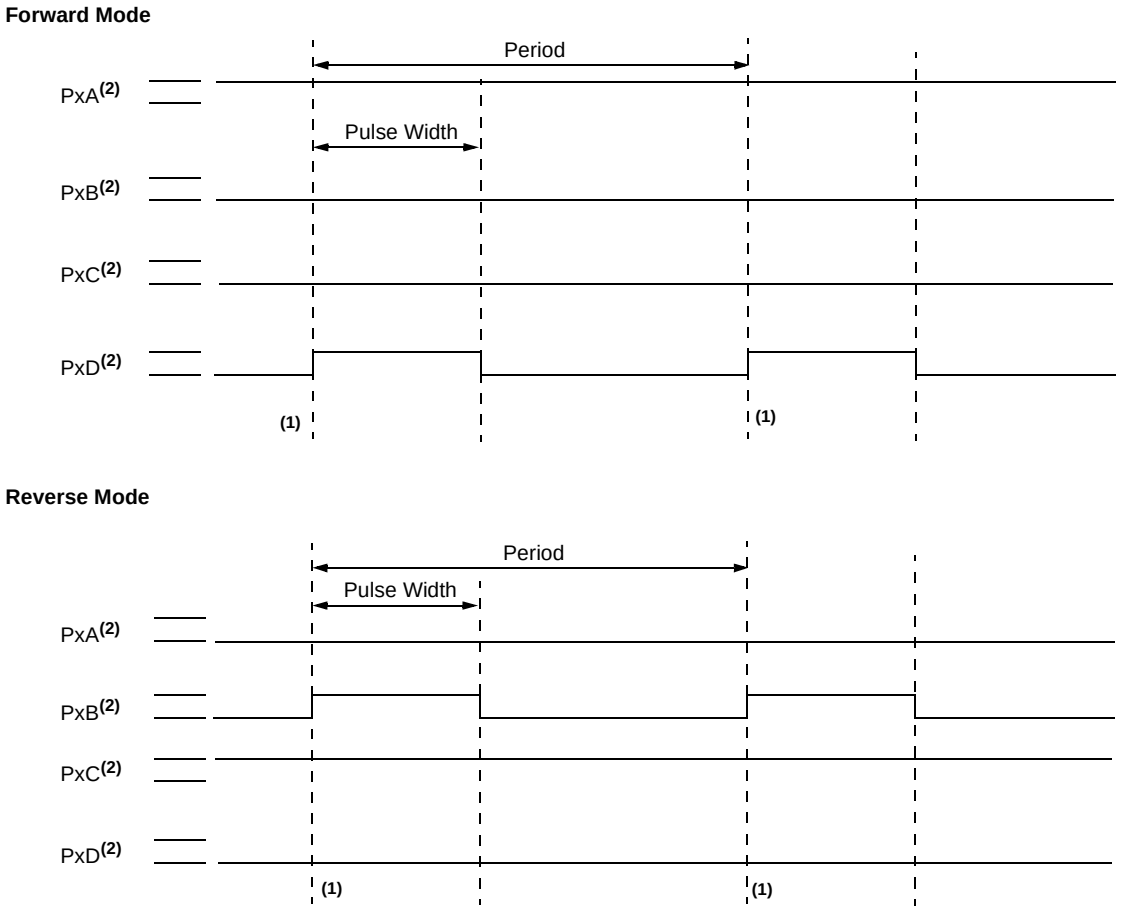
Note 1: These registers/bits are available on PIC18(L)F4XK22 devices.

TABLE 14-11: CONFIGURATION REGISTERS ASSOCIATED WITH STANDARD PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CONFIG3H	MCLRE	—	P2BMX	T3CMX	HFOFST	CCP3MX	PBADEN	CCP2MX	348

Legend: — = Unimplemented location, read as '0'. Shaded bits are not used by Standard PWM mode.

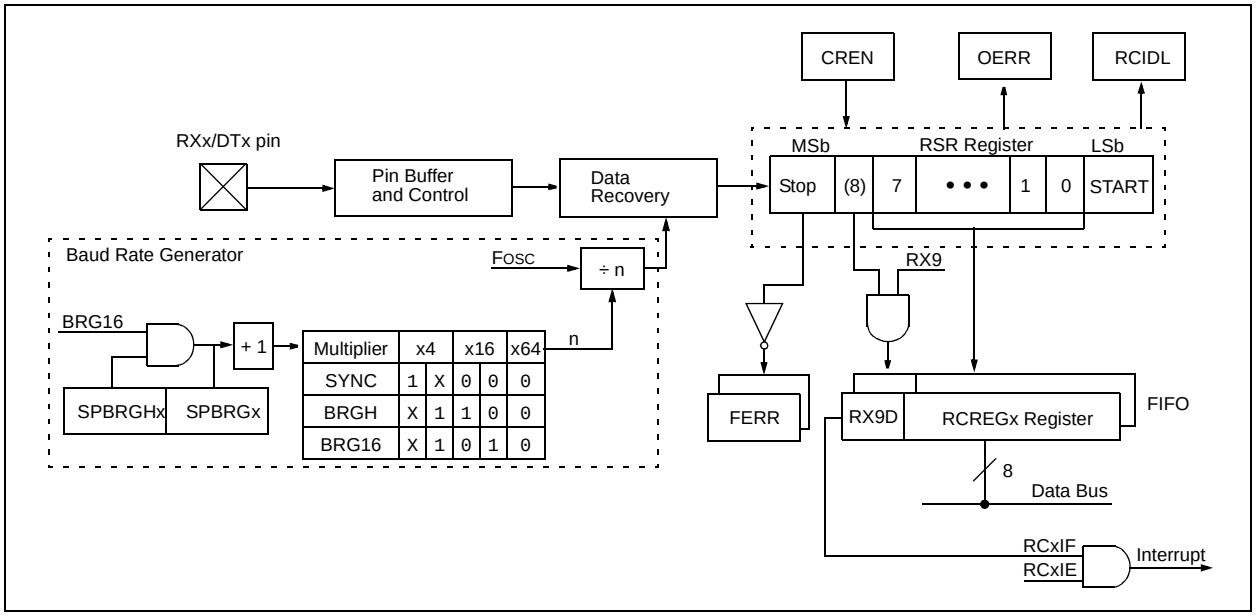
FIGURE 14-11: EXAMPLE OF FULL-BRIDGE PWM OUTPUT



Note 1: At this time, the TMRx register is equal to the PRx register.

2: Output signal is shown as active-high.

FIGURE 16-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTAx)
- Receive Status and Control (RCSTAx)
- Baud Rate Control (BAUDCONx)

These registers are detailed in Register 16-1, Register 16-2 and Register 16-3, respectively.

For all modes of EUSART operation, the TRIS control bits corresponding to the RXx/DTx and TXx/CKx pins should be set to '1'. The EUSART control will automatically reconfigure the pin from input to output, as needed.

When the receiver or transmitter section is not enabled then the corresponding RXx/DTx or TXx/CKx pin may be used for general purpose input and output.

TABLE 16-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 64.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	—	—	—
9600	—	—	—	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	—	—	—	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	207	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	57.97k	0.64	68	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	114.29k	-0.79	34	115.2k	0.00	9	111.1k	-3.55	8	115.2k	0.00	5

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SxBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)
300	—	—	—	—	—	—	—	—	—	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	FOSC = 64.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRGHx: SPBRGx (decimal)	Actual Rate	% Error	SPBRGHx: SPBRGx (decimal)	Actual Rate	% Error	SPBRGHx :SPBRGx (decimal)	Actual Rate	% Error	SPBRGHx: SPBRGx (decimal)
300	300.0	0.00	13332	300.0	0.00	3839	300.03	0.01	3332	300.0	0.00	2303
1200	1200.1	0.01	3332	1200	0.00	959	1200.5	0.04	832	1200	0.00	575
2400	2399	-0.02	1666	2400	0.00	479	2398	-0.08	416	2400	0.00	287
9600	9592	-0.08	416	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	10417	0.00	383	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	207	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	57.97k	0.64	68	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	114.29k	-0.79	34	115.2k	0.00	9	111.11k	-3.55	8	115.2k	0.00	5

17.4 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 17-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 17-5. The maximum recommended impedance for analog sources is 3 kΩ. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 17-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 17-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $3.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 5\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{2047}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{2047}\right) \quad ;\text{combining [1] and [2]}$$

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -13.5pF(1k\Omega + 700\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.20\mu s$$

Therefore:

$$T_{ACQ} = 5\mu s + 1.20\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 7.45\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

21.3 Register Definitions: FVR Control

REGISTER 21-1: VREFCON0: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-1	U-0	U-0	U-0	U-0
FVREN	FVRST	FVRS<1:0>		—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **FVREN:** Fixed Voltage Reference Enable bit
0 = Fixed Voltage Reference is disabled
1 = Fixed Voltage Reference is enabled

bit 6 **FVRST:** Fixed Voltage Reference Ready Flag bit
0 = Fixed Voltage Reference output is not ready or not enabled
1 = Fixed Voltage Reference output is ready for use

bit 5-4 **FVRS<1:0>:** Fixed Voltage Reference Selection bits
00 = Fixed Voltage Reference Peripheral output is off
01 = Fixed Voltage Reference Peripheral output is 1x (1.024V)
10 = Fixed Voltage Reference Peripheral output is 2x (2.048V)**(1)**
11 = Fixed Voltage Reference Peripheral output is 4x (4.096V)**(1)**

bit 3-2 **Reserved:** Read as '0'. Maintain these bits clear.

bit 1-0 **Unimplemented:** Read as '0'.

Note 1: Fixed Voltage Reference output cannot exceed V_{DD}.

TABLE 21-1: SUMMARY OF REGISTERS ASSOCIATED WITH FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
VREFCON0	FVREN	FVRST	FVRS<1:0>		—	—	—	—	332

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used by the FVR module.

24.0 SPECIAL FEATURES OF THE CPU

PIC18(L)F2X/4XK22 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These are:

- Oscillator Selection
- Resets:
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Code Protection
- ID Locations
- In-Circuit Serial Programming™

The oscillator can be configured for the application depending on frequency, power, accuracy and cost. All of the options are discussed in detail in **Section 2.0 "Oscillator Module (With Fail-Safe Clock Monitor)"**.

A complete discussion of device Resets and interrupts is available in previous sections of this data sheet.

In addition to their Power-up and Oscillator Start-up Timers provided for Resets, PIC18(L)F2X/4XK22 devices have a Watchdog Timer, which is either permanently enabled via the Configuration bits or software controlled (if configured as disabled).

The inclusion of an internal RC oscillator also provides the additional benefits of a Fail-Safe Clock Monitor (FSCM) and Two-Speed Start-up. FSCM provides for background monitoring of the peripheral clock and automatic switchover in the event of its failure. Two-Speed Start-up enables code to be executed almost immediately on start-up, while the primary clock source completes its start-up delays.

All of these features are enabled and configured by setting the appropriate Configuration register bits.

24.1 Configuration Bits

The Configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped starting at program memory location 300000h.

The user will note that address 300000h is beyond the user program memory space. In fact, it belongs to the configuration memory space (300000h-3FFFFFh), which can only be accessed using table reads and table writes.

Programming the Configuration registers is done in a manner similar to programming the Flash memory. The WR bit in the EECON1 register starts a self-timed write to the Configuration register. In Normal operation mode, a TBLWT instruction with the TBLPTR pointing to the Configuration register sets up the address and the data for the Configuration register write. Setting the WR bit starts a long write to the Configuration register. The Configuration registers are written a byte at a time. To write or erase a configuration cell, a TBLWT instruction can write a '1' or a '0' into the cell. For additional details on Flash programming, refer to **Section 6.6 "Writing to Flash Program Memory"**.

BTFSC **Bit Test File, Skip if Clear**

Syntax: BTFSC f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

1011	bbba	ffff	ffff

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped. If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh).
See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    BTFSC   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (TRUE)
If FLAG<1> = 1;
PC = address (FALSE)

BTFSS **Bit Test File, Skip if Set**

Syntax: BTFSS f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b < 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

1010	bbba	ffff	ffff

Description: If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh).
See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    BTFSS   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (FALSE)
If FLAG<1> = 1;
PC = address (TRUE)

GOTO **Unconditional Branch**

Syntax: GOTO k

Operands: $0 \le k \le 1048575$

Operation: $k \rightarrow PC<20:1>$

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	1111	k_7kkk	$kkkk_0$
2nd word(k<19:8>)	1111	$k_{19}kkk$	kkkk	$kkkk_8$

Description: GOTO allows an unconditional branch anywhere within entire 2-Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a 2-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: GOTO THERE

After Instruction
PC = Address (THERE)

INCF **Increment f**

Syntax: INCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0010	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: INCF CNT, 1, 0

Before Instruction
CNT = FFh
Z = 0
C = ?
DC = ?
After Instruction
CNT = 00h
Z = 1
C = 1
DC = 1

25.2.2 EXTENDED INSTRUCTION SET

ADDFSR **Add Literal to FSR**

Syntax: ADDFSR f, k

Operands: $0 \le k \le 63$
$f \in [0, 1, 2]$

Operation: FSR(f) + k → FSR(f)

Status Affected: None

Encoding:

1110	1000	ffkk	kkkk

Description: The 6-bit literal 'k' is added to the contents of the FSR specified by 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to FSR

Example: `ADDFSR 2, 23h`

Before Instruction
FSR2 = 03FFh
After Instruction
FSR2 = 0422h

ADDULNK **Add Literal to FSR2 and Return**

Syntax: ADDULNK k

Operands: $0 \le k \le 63$

Operation: FSR2 + k → FSR2,
(TOS) → PC

Status Affected: None

Encoding:

1110	1000	11kk	kkkk

Description: The 6-bit literal 'k' is added to the contents of FSR2. A RETURN is then executed by loading the PC with the TOS.
The instruction takes two cycles to execute; a NOP is performed during the second cycle.
This may be thought of as a special case of the ADDFSR instruction, where f = 3 (binary '11'); it operates only on FSR2.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to FSR
No Operation	No Operation	No Operation	No Operation

Example: `ADDULNK 23h`

Before Instruction
FSR2 = 03FFh
PC = 0100h
After Instruction
FSR2 = 0422h
PC = (TOS)

Note: All PIC18 instructions may take an optional label argument preceding the instruction mnemonic for use in symbolic addressing. If a label is used, the instruction syntax then becomes: {label} instruction argument(s).

27.4 DC Characteristics: RC Idle Supply Current, PIC18(L)F2X/4XK22 (Continued)

PIC18LF2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
PIC18F2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Device Characteristics**	**Typ**	**Max**	**Units**	**Conditions**		
D055		0.25	0.40	mA	-40°C to +125°C	VDD = 1.8V	FOSC = 1 MHz (**RC_IDLE** mode, HFINTOSC source)
D056		0.35	0.50	mA	-40°C to +125°C	VDD = 3.0V	
D057		0.30	0.45	mA	-40°C to +125°C	VDD = 2.3V	FOSC = 1 MHz (**RC_IDLE** mode, HFINTOSC source)
D058		0.40	0.50	mA	-40°C to +125°C	VDD = 3.0V	
D059		0.45	0.60	mA	-40°C to +125°C	VDD = 5.0V	
D060		0.50	0.7	mA	-40°C to +125°C	VDD = 1.8V	FOSC = 16 MHz (**RC_IDLE** mode, HFINTOSC source)
D061		0.80	1.1	mA	-40°C to +125°C	VDD = 3.0V	
D062		0.65	1.0	mA	-40°C to +125°C	VDD = 2.3V	FOSC = 16 MHz (**RC_IDLE** mode, HFINTOSC source)
D063		0.80	1.1	mA	-40°C to +125°C	VDD = 3.0V	
D064		0.95	1.2	mA	-40°C to +125°C	VDD = 5.0V	
D066		2.5	3.5	mA	-40°C to +125°C	VDD = 3.0V	FOSC = 64 MHz (**RC_IDLE** mode, HFINTOSC + PLL source)
D068		2.5	3.5	mA	-40°C to +125°C	VDD = 3.0V	FOSC = 64 MHz (**RC_IDLE** mode, HFINTOSC + PLL source)
D069		3.0	4.5	mA	-40°C to +125°C	VDD = 5.0V	

Note 1: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
Test condition: All Peripheral Module Control bits in PMD0, PMD1 and PMD2 set to '1'.

2: The test conditions for all IDD measurements in active operation mode are:
All I/O pins set as outputs driven to Vss;
$\overline{MCLR}$ = VDD;
OSC1 = external square wave, from rail-to-rail (PRI_RUN and PRI_IDLE only).

TABLE 27-16: I²C BUS DATA REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	Must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Must operate at a minimum of 10 MHz
			SSP Module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	Must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Must operate at a minimum of 10 MHz
			SSP Module	1.5 TCY	—		
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A fast mode I²C bus device can be used in a standard mode I²C bus system but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the standard mode I²C bus specification), before the SCL line is released.

FIGURE 28-34: PIC18LF2X/4XK22 TYPICAL IDD: RC_IDLE LF-INTOSC 31 kHz

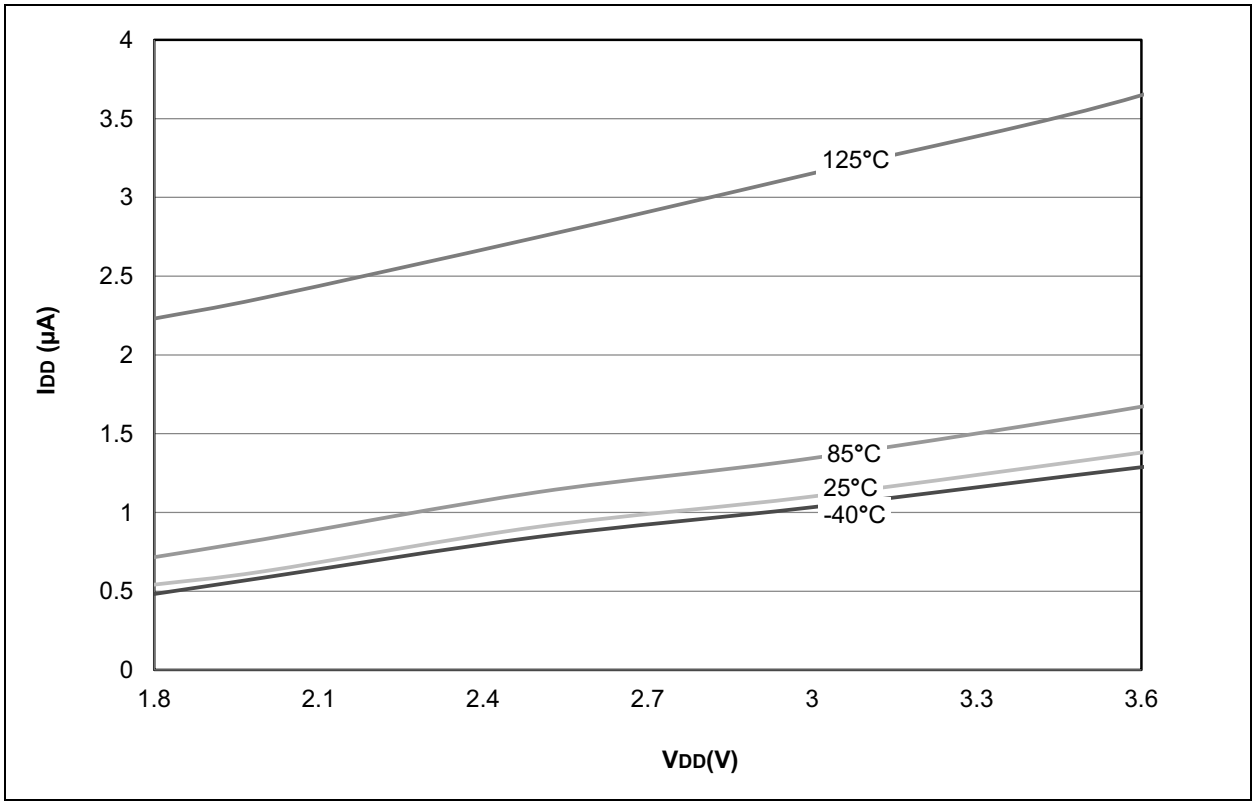


FIGURE 28-35: PIC18LF2X/4XK22 MAXIMUM IDD: RC_IDLE LF-INTOSC 31 kHz

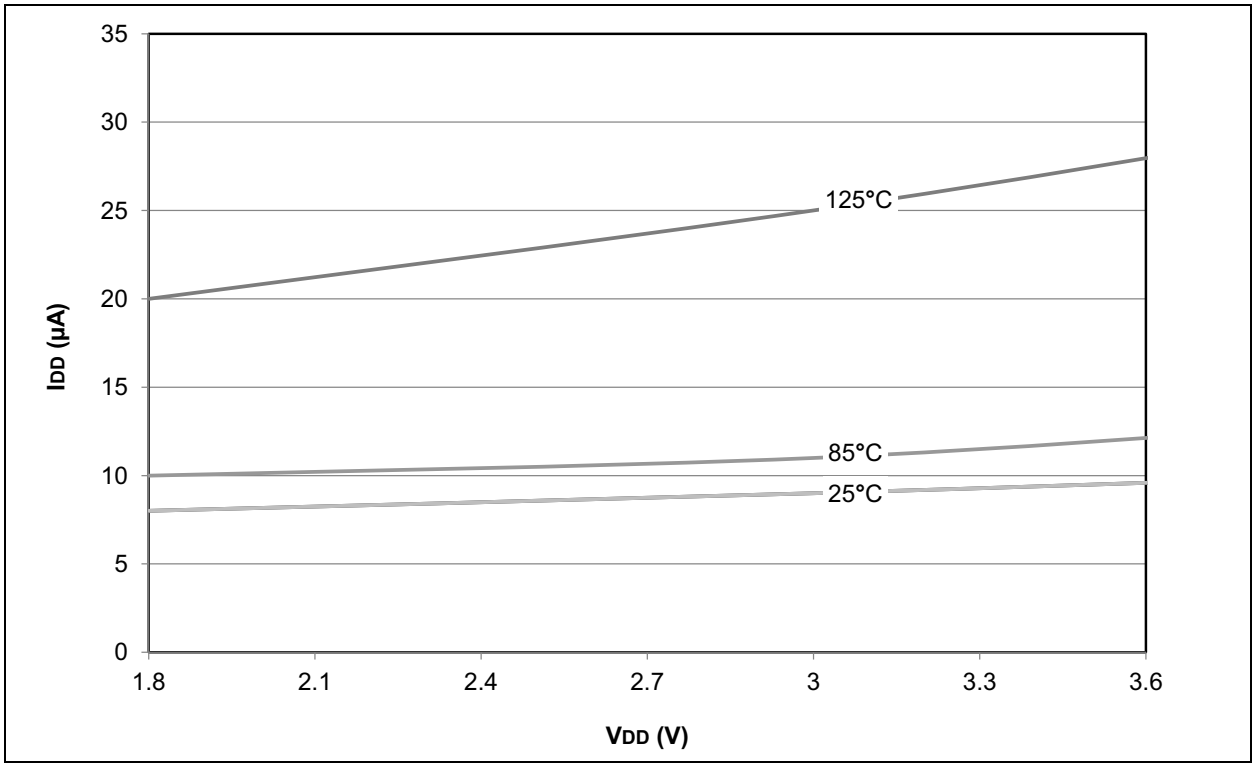


FIGURE 28-54: PIC18F2X/4XK22 TYPICAL IDD: PRI_RUN EC HIGH POWER

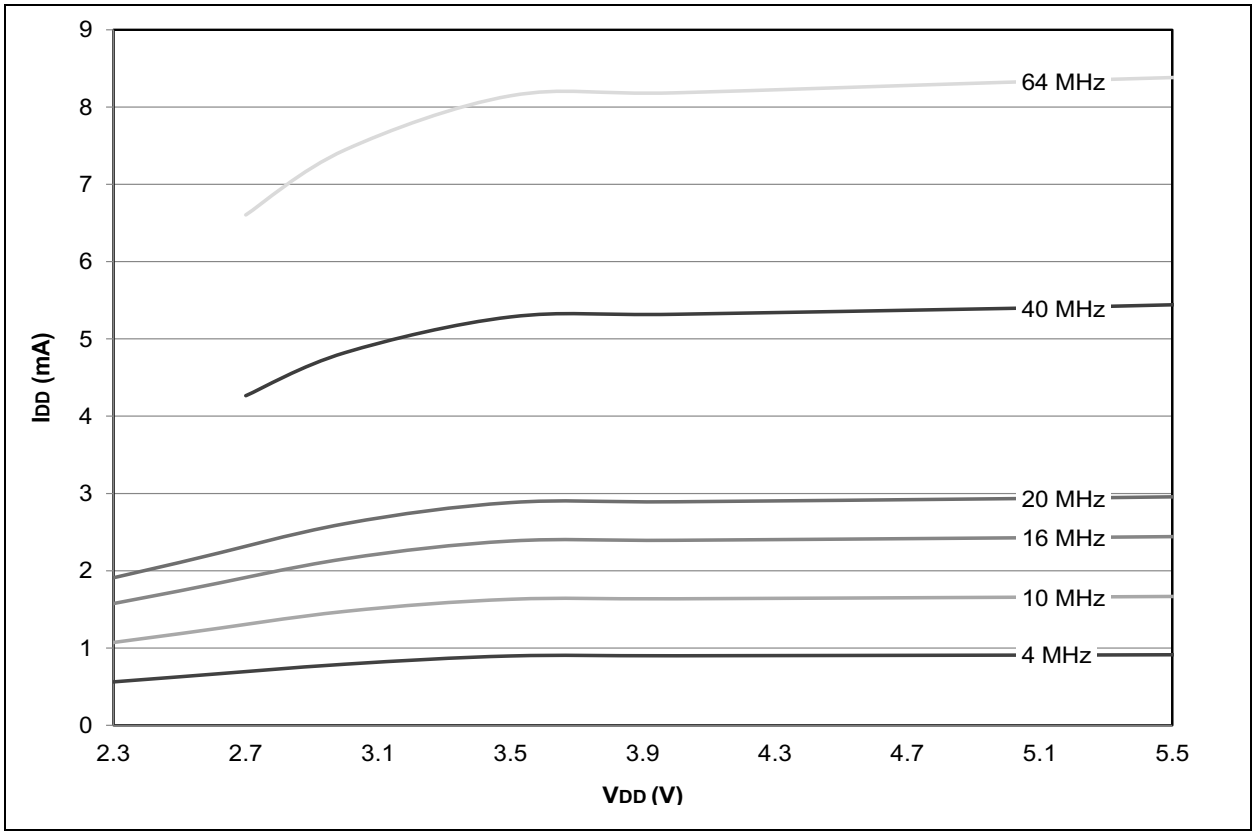
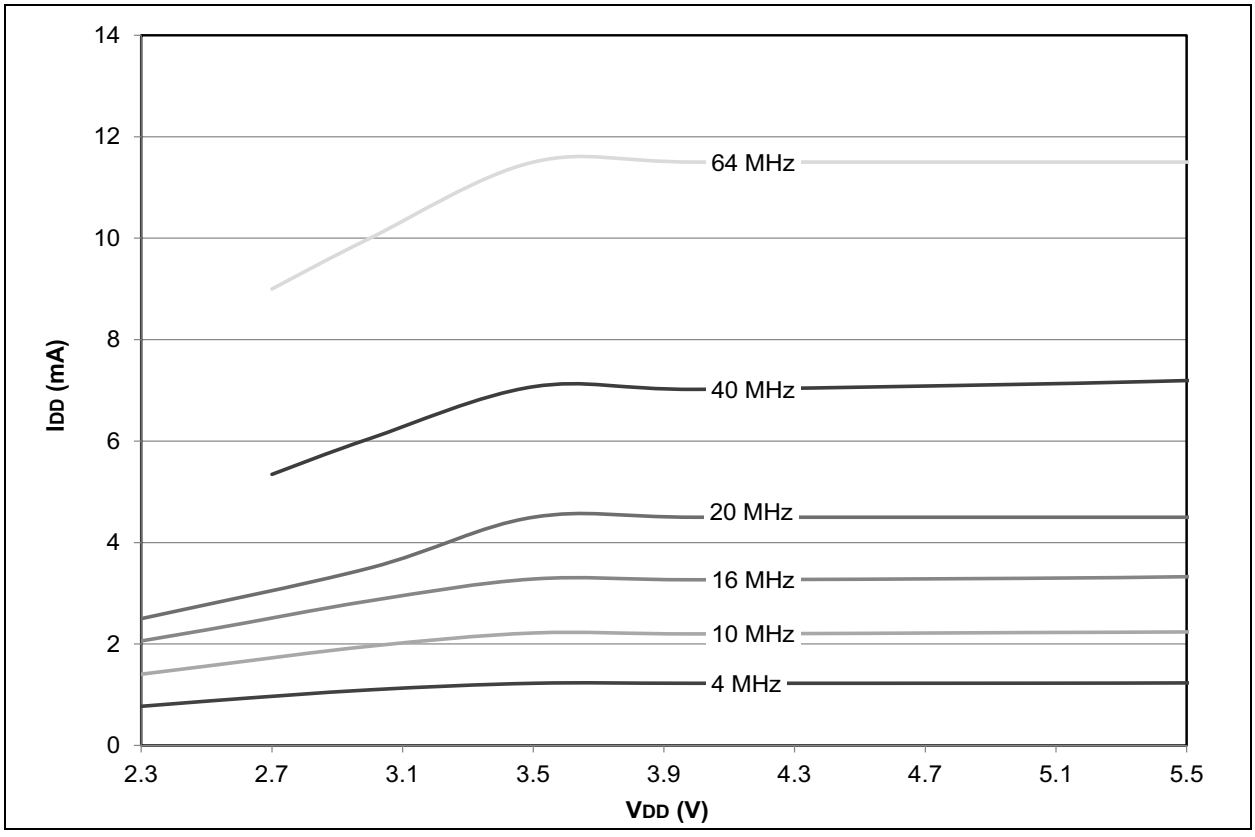
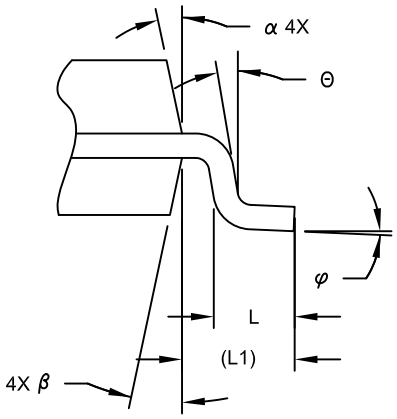


FIGURE 28-55: PIC18F2X/4XK22 MAXIMUM IDD: PRI_RUN EC HIGH POWER

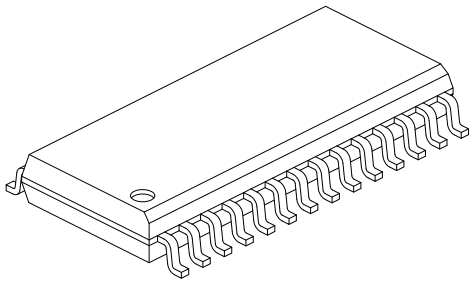


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features[1]	PIC18F23K22 PIC18LF23K22	PIC18F24K22 PIC18LF24K22	PIC18F25K22 PIC18LF25K22	PIC18F26K22 PIC18LF26K22	PIC18F43K22 PIC18LF43K22	PIC18F44K22 PIC18LF44K22	PIC18F45K22 PIC18LF45K22	PIC18F46K22 PIC18LF46K22
Program Memory (Bytes)	8192	16384	32768	65536	8192	16384	32768	65536
SRAM (Bytes)	512	768	1536	3896	512	768	1536	3896
EEPROM (Bytes)	256	256	256	1024	256	256	256	1024
Interrupt Sources	26	26	33	33	26	26	33	33
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules (CCP)	2	2	2	2	2	2	2	2
Enhanced CCP Modules (ECCP) Full Bridge	1	1	1	1	2	2	2	2
ECCP Module Half Bridge	2	2	2	2	1	1	1	1
10-bit Analog-to-Digital Module	17 input channels	17 input channels	17 input channels	17 input channels	28 input channels	28 input channels	28 input channels	28 input channels
Packages	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin QFN 28-pin UQFN	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin QFN 28-pin UQFN	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin QFN	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin QFN	40-pin PDIP 40-pin UQFN 44-pin TQFP 44-pin QFN	40-pin PDIP 40-pin UQFN 44-pin TQFP 44-pin QFN	40-pin PDIP 40-pin UQFN 44-pin TQFP 44-pin QFN	40-pin PDIP 40-pin UQFN 44-pin TQFP 44-pin QFN

Note 1: PIC18FXXK22: operating voltage, 2.3V-5.5V.

PIC18LFXXK22: operating voltage, 1.8V-3.6V.